ON Semiconductor

PRODUCT BULLETIN # 16724

Generic Copy

Issue Date: 13-Sep-2011

TITLE: SOT 223 VHVIC MSL Change from 3 to 1

PROPOSED FIRST SHIP DATE: 06-Oct-2011

AFFECTED CHANGE CATEGORY(S): Die bond epoxy material

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor sales office or Wl Chin<r46610@onsemi.com>

NOTIFICATION TYPE:
ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

SOT 223 VHVIC continuous improvement activity which enabled the change from MSL3 260 degree C to MSL1 260 degree C.

List of affected General Parts:

PARTS		
NCP1010ST100T3G	NCP1013ST65T3G	NCP1052ST100T3G
NCP1010ST130T3G	NCP1014ST100T3G	NCP1052ST136T3G
NCP1010ST65T3G	NCP1014ST65T3G	NCP1052ST44T3G
NCP1011ST100T3G	NCP1015ST100T3G	NCP1053ST100T3G
NCP1011ST130T3G	NCP1015ST65T3G	NCP1053ST136T3G
NCP1011ST65T3G	NCP1050ST100T3G	NCP1053ST44T3G
NCP1012ST100T3G	NCP1050ST136T3G	NCP1054ST100T3G
NCP1012ST130T3G	NCP1050ST44T3G	NCP1054ST136T3G
NCP1012ST65T3G	NCP1051ST100T3G	NCP1054ST44T3G
NCP1013ST100T3G	NCP1051ST136T3G	NCP1055ST100T3G
NCP1013ST130T3G	NCP1051ST44T3G	NCP1055ST136T3G
		NCP1055ST44T3G